

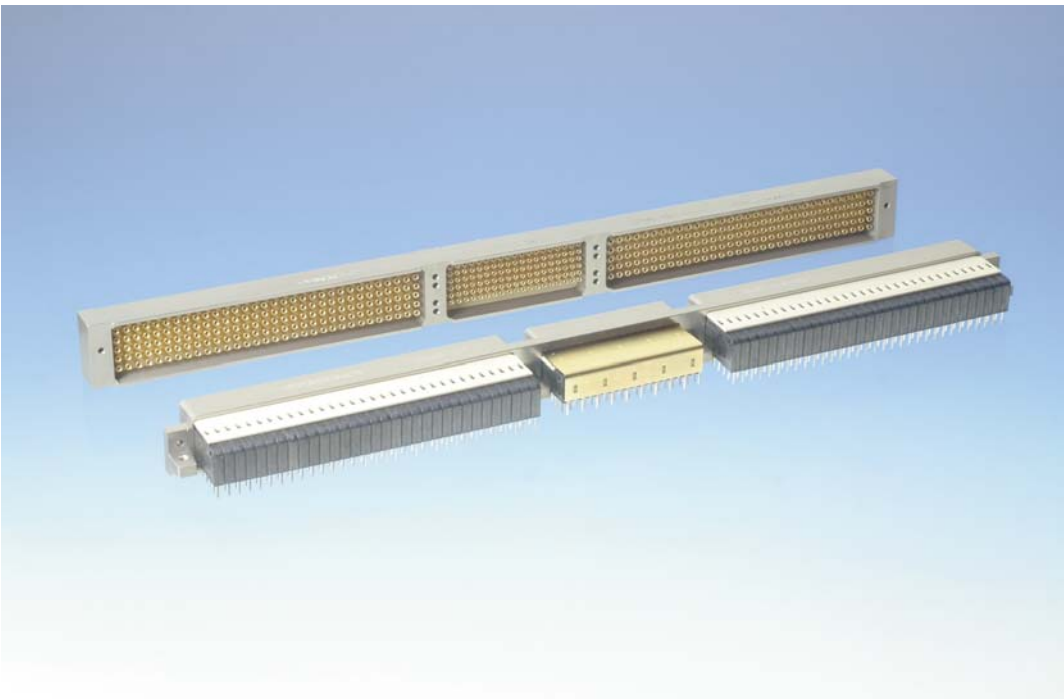
When failure is not an option.



Product Review

VME64x Connectors

Where Reliability and Speed of Data Transfer are a Necessity



Ruggedized Interconnect with High Signal Integrity

High Speed Signal Applications PO/JO Bay Tested to 3.125 Gb/s

Highly Reliable Hypertac® Contacts

Up to 100,000 Mating Cycles

Low Insertion and Extraction Forces

Ruggedized VME64x Connectors Overcome Challenges of Harsh Environments

Hypertronics' ruggedized VME64x interconnect solution comprises optimized contact lead traces, which provide superior performance in high-speed signal applications.

VME64x connectors are mechanically compliant with IEEE-1101.2 - 1992, supporting the premier embedded bus architecture. Aluminum frames provide ruggedness and condition cooling, and keying features ensure proper mating.

The physical demands of critical applications require a higher standard of reliability, and off-the-shelf connectors cannot stand up to the rigors of these types of applications where system failure is simply not an option. With the VME64x connector, Hypertronics' engineers have put together a complete solution that

removes weakness of the electrical interface from the standard VME COTS architecture, reducing the costs of developments, manufacturing, and ownership.

VME64x connectors include the highly reliable Hypertac contact technology, which offers a significantly improved interface for immunity to shock and vibration and low mating forces. Hypertac contact technology features a hyperboloid-shaped basket of individual spring wires that deliver the highest level of reliability and performance.

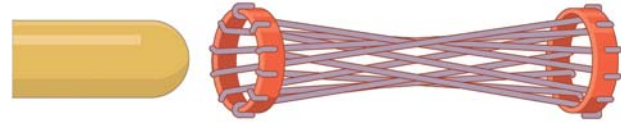
Hypertronics offers both standard and customizable VME64x solutions. With VME64x connectors, manufacturers with critical applications are guaranteed reliable, high-performance connector solutions for situations in which the cost of failure is incalculable.

Ruggedized VME64x Connectors

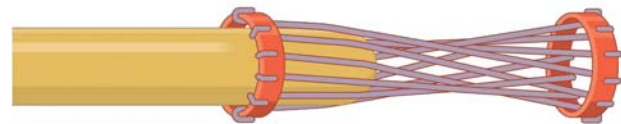
Features

- COTS and custom applications
- Designed for severe environments with high levels of shock and vibration
- Compatible with IEEE-1101.2 -1992
- Complies with ANSI/VITA 1.7 high current standard for VME64x
- Stackable design of high speed modules feature round pins to mate with Hypertac contacts
- Optimized lead traces within modules provide superior performance in high speed applications tested up to 3.125 Gb/s
- Aluminum frames for ruggedness and conduction cooling
- Keying feature ensures proper mating

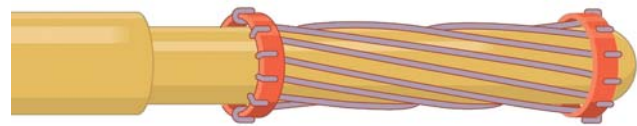
Hypertac Contact System



Wire sleeve before insertion of pin



Pin partially inserted into sleeve



Pin completely inserted into sleeve

General Specifications				
	<i>P1 / P2</i>	<i>P0</i>	<i>J1 / J2</i>	<i>J0</i>
Design criteria	IEEE-1101.2 1992			
Contact gender	Male pin		Hypertac .5mm socket	Hypertac .4mm socket
Contact termination style	Solder tail		Solder or press-fit	
Contact spacing	2.54 mm (5 row)	2 mm (6 row 5 + 1 shield row)	2.54 mm (5 row)	2 mm (6 row)
Contact current rating	2.5 amps	1 amp	2.5 amps	1 amp
Temperature range	minus -55 C to + 125 C			
Insulation resistance	>5000 megohm			
Insulator material	30 % glass filled LCP			
Flammability rating	94 V-0			
Pin contact material	BeCu			
Socket contact material			BeCu wires / brass body	
Plating mating contacts	50 micro-inch gold / 50 micro-inch nickel			
Plating contact termination	Tin lead (60- 40) / 50 micro inch nickel (MIL-P-81728)			
Suggested PCB hole diameter solder tail	1.00 mm +/- 0.05 mm after plating	0.75 mm +/- 0.05 mm after plating	1.00 mm +/- 0.05 mm after plating	0.60 mm +/- 0.05 mm after plating
Suggested PCB hole press fit compliant tail			1.00mm +/- 0.05 after plating	0.70 mm +/- 0.05 mm after plating



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HYP-007-0707

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